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MULTIPIN STRUCTURES.

Title (de)
Mehrstiftestruktur.

Title (fr)
STRUCTURES MULTIBROCHES.

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Application
EP 93913366 A 19930614

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• GB 9301265 W 19930614
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Abstract (en)
[origin: WO9325332A1] A heat sink comprises a thick base plate (1), a plurality of parallel pins (2) running outwardly from the base plate and spaced close to each other to define a labyrinthine air path, and a guide plate (3) in which an axial fan (4) is mounted to direct air parallel to the pins towards the base plate (1) which is mounted on the object to be cooled. The heat sink is produced by solidifying a mould (15) of resin coated sand around a tool (11-14), then withdrawing the tool, then gravity die casting through the mould, then destroying the mould.

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